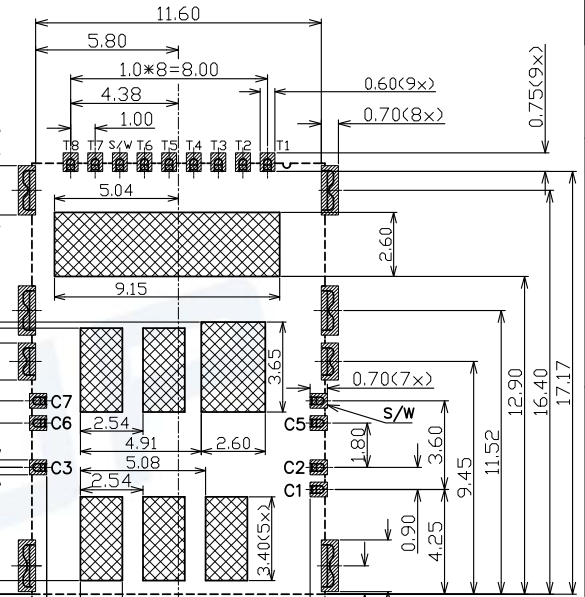
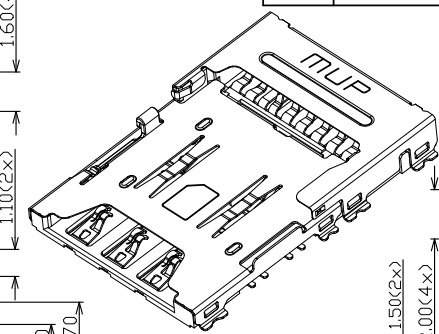
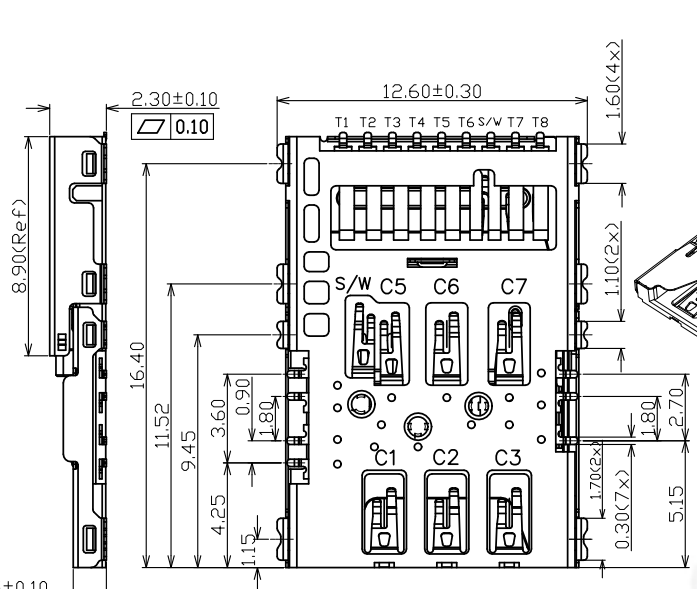
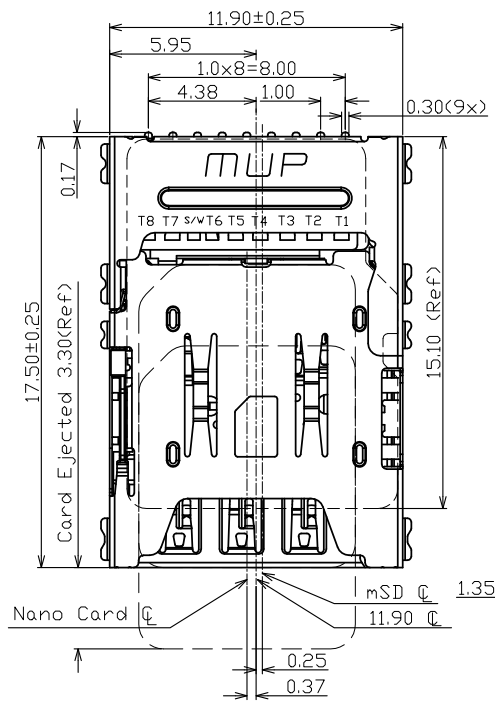


| REV. | DESCRIPTION OF REVISIONS | APPR. | DRAW. | RELEASE | DATE        |
|------|--------------------------|-------|-------|---------|-------------|
| X1   | NEW REVISION             |       |       |         | Jun.08.2020 |
| X2   |                          |       |       |         |             |



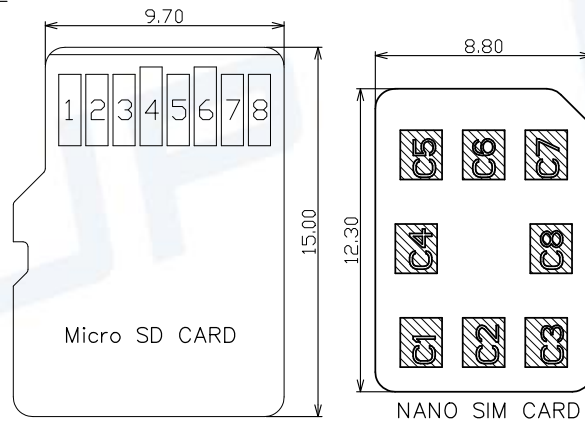
| MICRO SD CARD | PIN No. | ASSIGNMENT     |
|---------------|---------|----------------|
|               | 5       | CLK            |
|               | 1       | DAT2           |
|               | 2       | CD/DAT3        |
|               | 3       | CMD            |
|               | 4       | VDD            |
|               | s/w     | CARD DETECTION |

CIRCUIT DIAGRAM FOR DETECTION OF MICROSD CARD

| ELECTRIC FUNCTION | DETECT SWITCH | CIRCUIT MICROSD T6PIN SWITCH PIN |
|-------------------|---------------|----------------------------------|
| WITHOUT CARD      | OPEN          |                                  |
| CARD INSERTED     | CLOSED        |                                  |

CIRCUIT DIAGRAM FOR DETECTION OF NANO SIM CARD

| ELECTRIC FUNCTION | DETECT SWITCH | CIRCUIT NANO C5PIN SWITCH PIN |
|-------------------|---------------|-------------------------------|
| WITHOUT CARD      | OPEN          |                               |
| CARD INSERTED     | CLOSED        |                               |



**TECHNICAL CHARACTERISTICS**  
 1.General Characteristics  
 Dimensions:17.50LX11.90WX2.30H mm  
 Weight: Approx 0.5g  
 Durability:3,000 cycles min.  
 2.Electrical Characteristics  
 Contact resistance:50mΩ typical, 100mΩMax  
 Insulation resistance:>1000m/500V DC  
 3.Solderability  
 Vaporphase:±215°C, 30sec.Max  
 IR reflow:260°C,5~10sec.Max  
 Manual soldering:370°C.3sec.Max  
 4.Environmental Characteristics  
 Operating temperature:-25°C~+85°C  
 Storage Temperature :-40°C~+85°C  
 Operating humidity:10%~+95%RH

| NAND SIM CARD |                |
|---------------|----------------|
| PIN No.       | ASSIGNMENT     |
| C1            | VCC            |
| C2            | RST            |
| C3            | CLK            |
| C5            | GND            |
| C6            | VPP            |
| C7            | I/O            |
| s/w           | CARD DETECTION |

| ITEM | PART NAME    | Q'TY | MATERIAL              | FINISH                   |
|------|--------------|------|-----------------------|--------------------------|
| 1    | HOUSING      | 1    | Hi-temp Thermoplastic | Black UL94V-0            |
| 2    | DATA CONTACT | 14   | Copper Alloy          | Contact area:Gold plated |
| 3    | SWITCH       | 2    | Copper Alloy          | Contact area:Gold plated |
| 4    | SHELL        | 2    | Stainless Steel       | Solder area:Gold plated  |
| 5    | PULLER       | 1    | Stainless Steel       |                          |

Unless otherwise specified, other tolerance are:  
 X ±0.35 X\* ±5°  
 X.X ±0.25 X.X\* ±4°  
 X.XX ±0.15 X.XX\* ±3°  
 X.XXX ±0.10 X.XXX\* ±2°  
 PROJ. UNIT mm SCALE 1:1  
 CUSTOMER DRAWING

**MUP MUP INDUSTRIAL CO.,LTD.**

NAME: **MICRO SD+NANO SIM Card Connector**  
 MODEL NO: **MUP-M6102-1**  
 TYPE : **MICRO SD+NANO SIM WITH S/W 2.30H PULLER TYPE**

|          |                   |          |                 |
|----------|-------------------|----------|-----------------|
| DRAWN    | Henry Aug.12.2019 | DWG NO.: | DWG-MUP-M6102-1 |
| CHECKED  | Henry Aug.12.2019 | SHEET    | 1/1             |
| APPROVAL | Simon Aug.12.2019 | REVISION | X1              |

